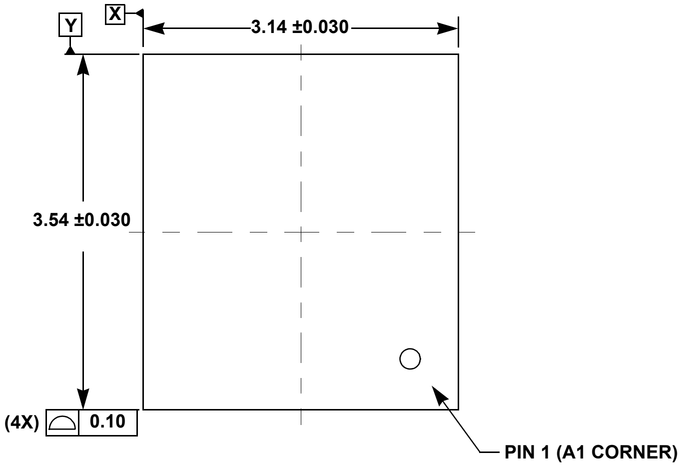
Package Outline Drawing

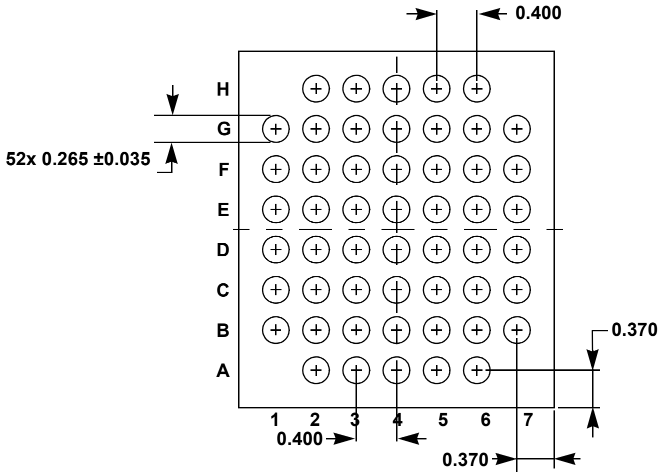
W7x8.52

7X8 ARRAY 52 BALLS WITH 0.40 PITCH WAFER LEVEL CHIP SCALE PACKAGE

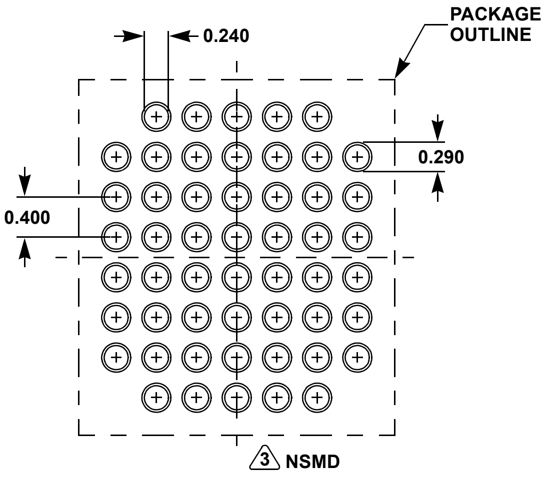
Rev 1, 10/14



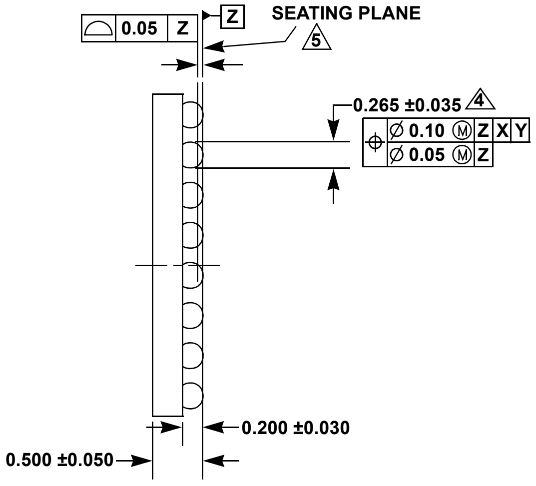
TOP VIEW



BOTTOM VIEW



TYPICAL RECOMMENDED LAND PATTERN



SIDE VIEW

NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerance per ASME Y 14.5M - 1994, and JESD 95-1 SPP-010.
3. NSMD refers to non-solder mask defined pad design per Intersil Techbrief TB451.
4. Dimension is measured at the maximum bump diameter parallel to primary datum Z.
5. Primary datum Z and seating plane are defined by the spherical crowns of the bump.